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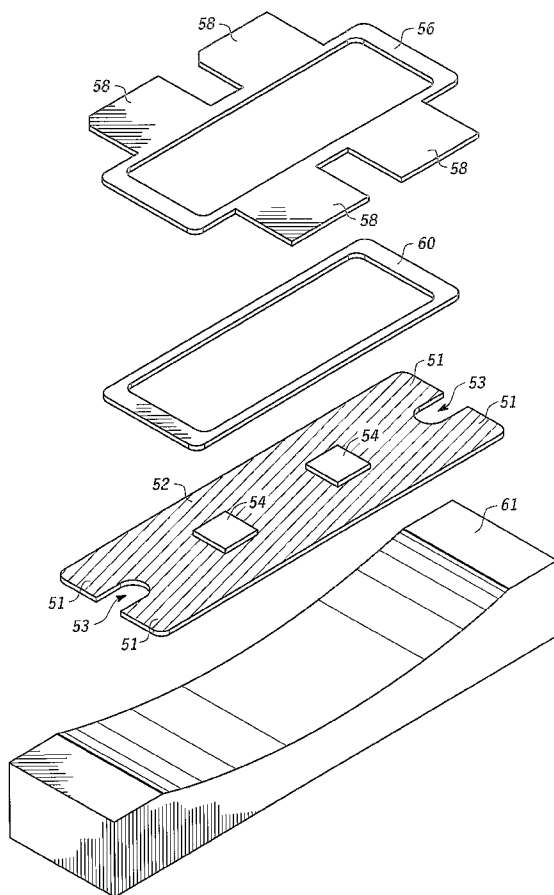
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(54) Title: METHOD OF ASSEMBLING A SEMICONDUCTOR COMPONENT AND APPARATUS THEREFOR



(57) Abstract: A method of assembling a semiconductor component includes providing a pedestal (61), placing a first piece (52) on the pedestal, wherein the first piece comprises a semiconductor die (54), placing a second piece (56, 58) over the first piece, and providing an adhesive (60) between the first piece and the second piece. The method further includes applying pressure with a first plate to the first piece and second piece to snap the first piece with the second piece, and applying heat with a second plate to reflow the adhesive, wherein applying heat is performed simultaneously with applying pressure.



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